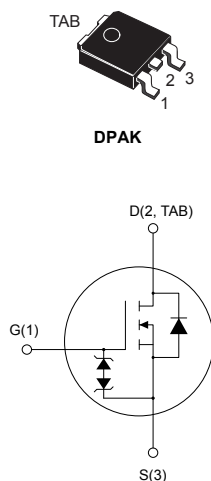


N-channel 620 V, 950 mΩ typ., 5.5 A MDmesh K3 Power MOSFET in a DPAK package



AM01476v1_tab



Features

Order codes	V_{DS}	$R_{DS(on)}$ max.	I_D	P_{TOT}
STD6N62K3	620 V	1.2 Ω	5.5 A	90 W

- 100% avalanche tested
- Extremely high dv/dt capability
- Very low intrinsic capacitance
- Improved diode reverse recovery characteristics
- Zener-protected

Applications

- Switching applications

Description

This MDmesh K3 Power MOSFET is the result of improvements applied to STMicroelectronics' MDmesh technology, combined with a new optimized vertical structure. This device boasts an extremely low on-resistance, superior dynamic performance and high avalanche capability, rendering it suitable for the most demanding applications.

Product status link

[STD6N62K3](#)

Product summary

Order code	STD6N62K3
Marking	6N62K3
Package	DPAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	620	V
V_{GS}	Gate-source voltage	± 30	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^{\circ}\text{C}$	5.5	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^{\circ}\text{C}$	3	A
$I_{DM}^{(1)}$	Drain current (pulsed)	22	A
P_{TOT}	Total power dissipation at $T_C = 25\text{ }^{\circ}\text{C}$	90	W
$I_{AR}^{(2)}$	Avalanche current, repetitive or not-repetitive	5.5	A
$E_{AS}^{(3)}$	Single pulse avalanche energy	140	mJ
ESD	Gate-source human body model ($R = 1.5\text{ k}\Omega$, $C = 100\text{ pF}$)	2.5	kV
$dv/dt^{(4)}$	Peak diode recovery voltage slope	12	V/ns
T_{stg}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$
T_j	Operating junction temperature range		

1. Pulse width limited by safe operating area.
2. Pulse width limited by T_j max.
3. Starting $T_j = 25\text{ }^{\circ}\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50\text{ V}$.
4. $I_{SD} \leq 5.5\text{ A}$, $di/dt \leq 400\text{ A}/\mu\text{s}$, $V_{DD} = 80\% V_{(BR)DSS}$.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJC}	Thermal resistance, junction-to-case	1.39	$^{\circ}\text{C}/\text{W}$
$R_{thJA}^{(1)}$	Thermal resistance junction-to-ambient	50	$^{\circ}\text{C}/\text{W}$

1. When mounted on 1inch² FR-4 board, 2 oz Cu.

2 Electrical characteristics

($T_C = 25\text{ }^{\circ}\text{C}$ unless otherwise specified).

Table 3. On /off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$	620			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 620\text{ V}$			0.8	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 620\text{ V}$ $T_C = 125\text{ }^{\circ}\text{C}$ ⁽¹⁾			50	μA
I_{GSS}	Gate body leakage current	$V_{GS} = \pm 20\text{ V}$, $V_{DS} = 0\text{ V}$			± 9	μA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 50\text{ }\mu\text{A}$	3	3.75	4.5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$, $I_D = 2.8\text{ A}$		0.95	1.2	Ω

1. Specified by design, not tested in production.

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 50\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	875	-	pF
C_{oss}	Output capacitance			100		
C_{rss}	Reverse transfer capacitance			17		
$C_{o(er)}^{(1)}$	Equivalent output capacitance energy related	$V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ to }480\text{ V}$	-	28	-	pF
$C_{o(tr)}^{(2)}$	Equivalent output capacitance time related			63		
R_G	Intrinsic gate resistance	$f = 1\text{ MHz}$ open drain	-	3.5	-	Ω
Q_g	Total gate charge	$V_{DD} = 496\text{ V}$, $I_D = 5.5\text{ A}$, $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 15. Test circuit for gate charge behavior)	-	34	-	nC
Q_{gs}	Gate-source charge			4		
Q_{gd}	Gate-drain charge			22		

1. $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

2. $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 310\text{ V}$, $I_D = 2.75\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ (see Figure 14. Test circuit for resistive load switching times and Figure 19. Switching time waveform)	-	22	-	ns
t_r	Rise time			12		
$t_{d(off)}$	Turn-off delay time			49		
t_f	Fall time			20		

Table 6. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		5.5	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				27	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 5.5 \text{ A}$, $V_{GS} = 0 \text{ V}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 5.5 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	290		ns
Q_{rr}	Reverse recovery charge			1.9		μC
I_{RRM}	Reverse recovery current			13.5		A
t_{rr}	Reverse recovery time	$I_{SD} = 5.5 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$, $T_j = 150 \text{ }^\circ\text{C}$ (see Figure 16. Test circuit for inductive load switching and diode recovery times)	-	335		ns
Q_{rr}	Reverse recovery charge			2.4		μC
I_{RRM}	Reverse recovery current			14.5		A

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics curves

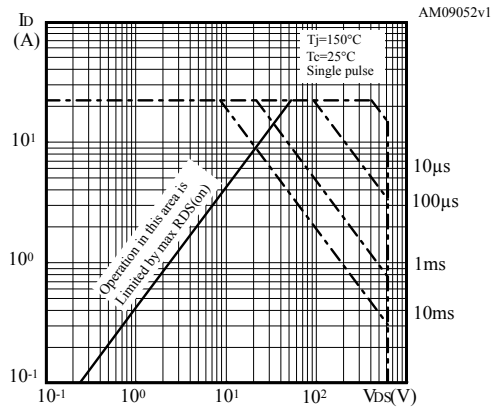
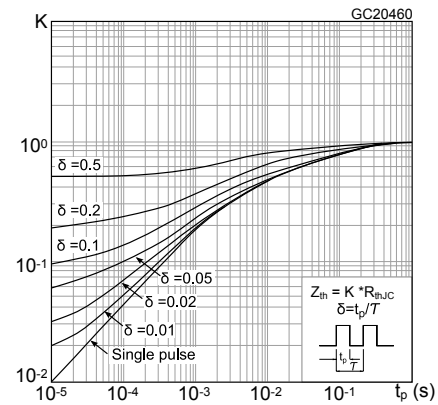
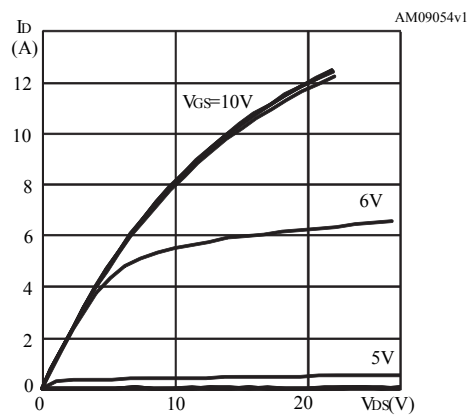
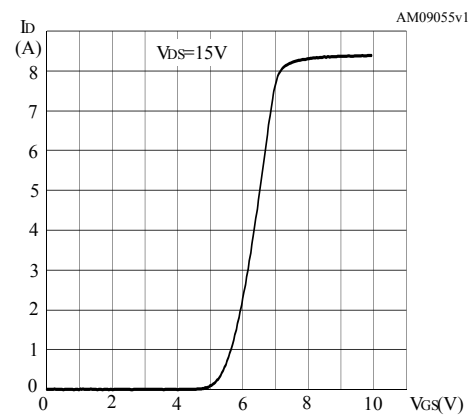
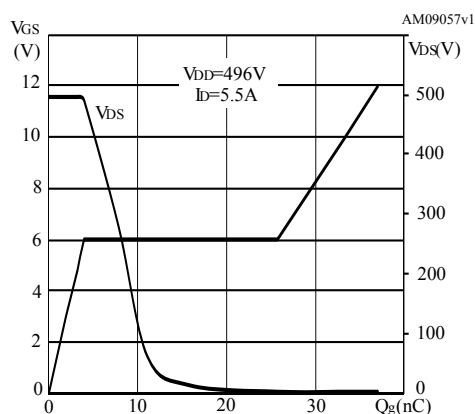
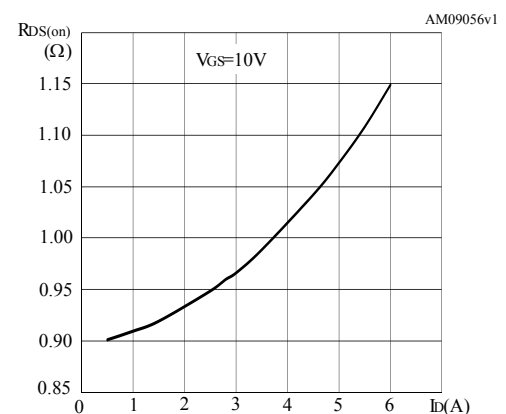
Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Gate charge vs gate-source voltage

Figure 6. Static drain-source on resistance


Figure 7. Capacitance variations

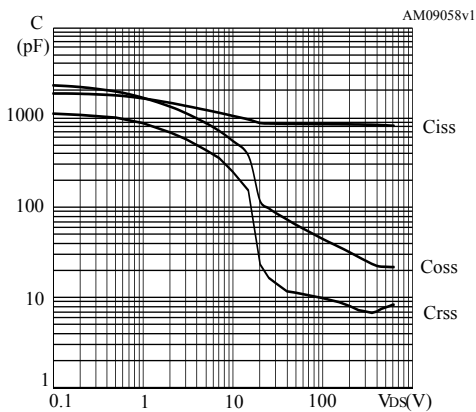


Figure 8. Output capacitance stored energy

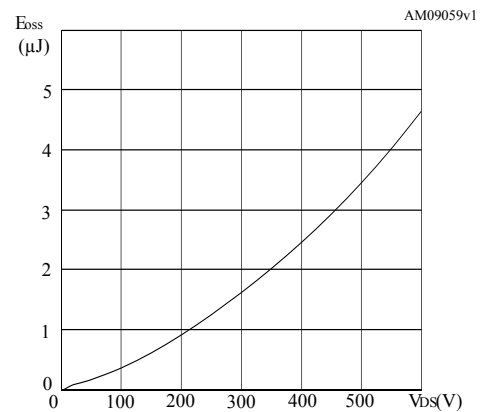


Figure 9. Normalized gate threshold voltage vs temperature

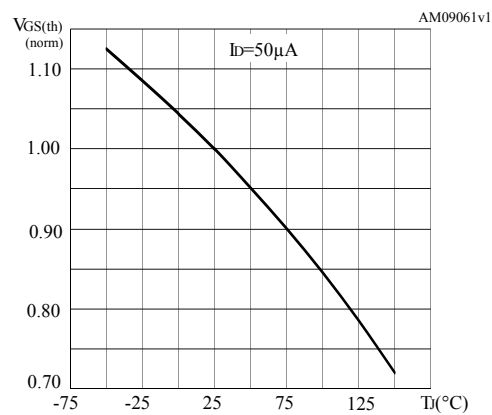


Figure 10. Normalized on resistance vs temperature

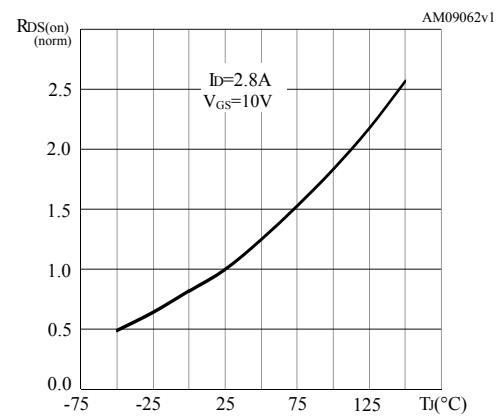


Figure 11. Normalized BVDS vs temperature

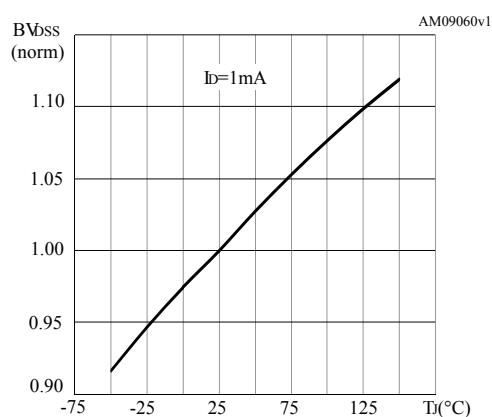


Figure 12. Source-drain diode forward characteristics

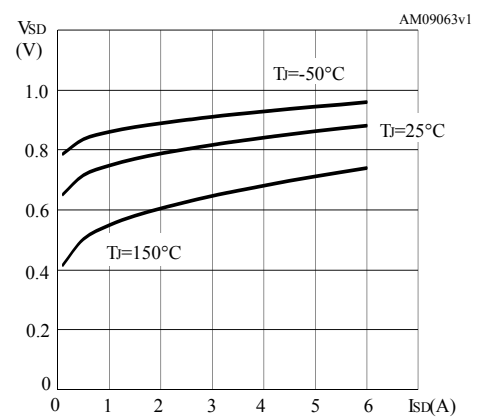
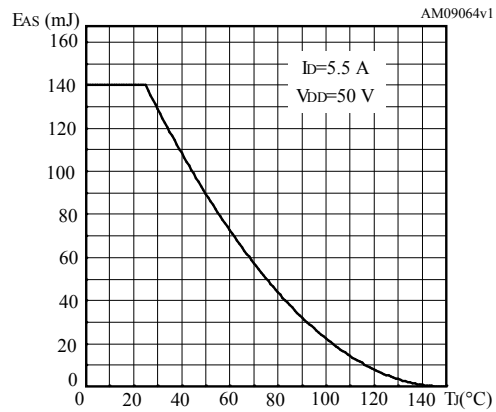
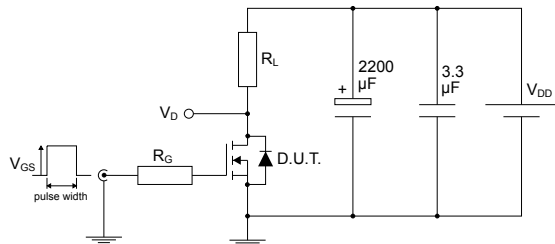


Figure 13. Maximum avalanche energy vs temperature



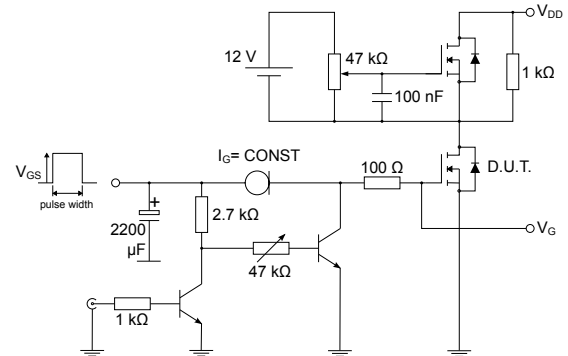
3 Test circuits

Figure 14. Test circuit for resistive load switching times



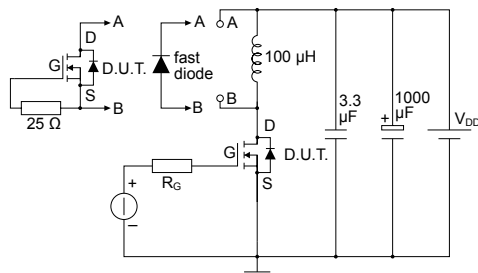
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Figure 15. Test circuit for gate charge behavior



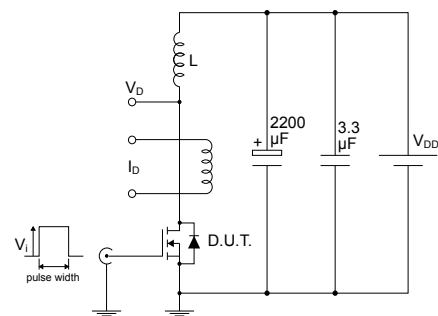
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Figure 16. Test circuit for inductive load switching and diode recovery times



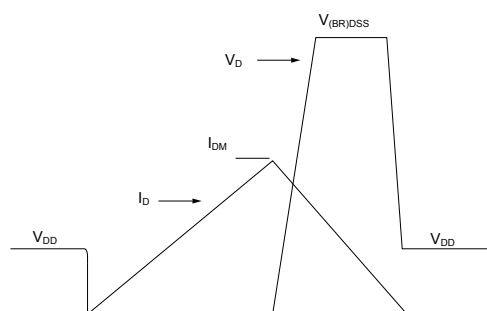
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Figure 17. Unclamped inductive load test circuit



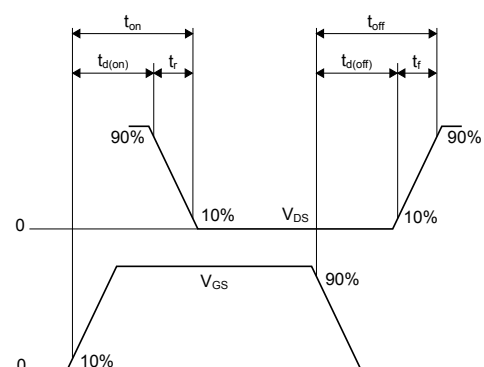
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Figure 18. Unclamped inductive waveform



AM01472v1

Figure 19. Switching time waveform



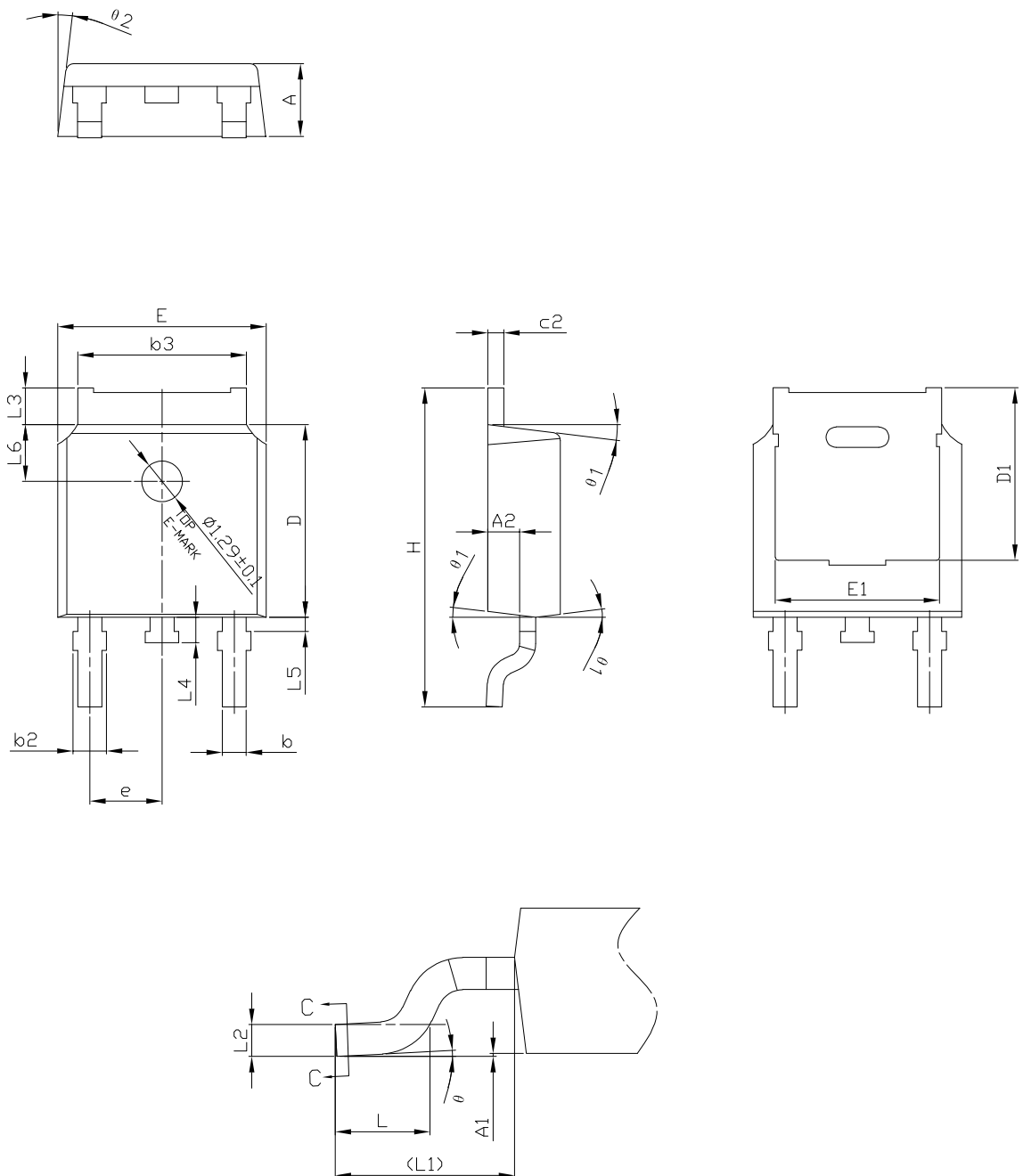
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

4.1 DPAK (TO-252) type C3 package information

Figure 20. DPAK (TO-252) type C3 package outline



0068772_type-C3_rev34

Table 7. DPAK (TO-252) type C3 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.00		0.10
A2	0.90	1.01	1.10
b	0.72		0.85
b2	0.72		1.10
b3	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.20	5.45	5.70
E	6.50	6.60	6.70
E1	5.00	5.20	5.40
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.51 BSC		
L3	0.90		1.25
L4	0.60	0.80	1.00
L5	0.15		0.75
L6	1.80 REF		
θ	0°		8°
θ1	5°	7°	9°
θ2	5°	7°	9°

Technical drawing of a mechanical part, likely a cross-section of a shaft or a similar component. The drawing includes the following dimensions and features:

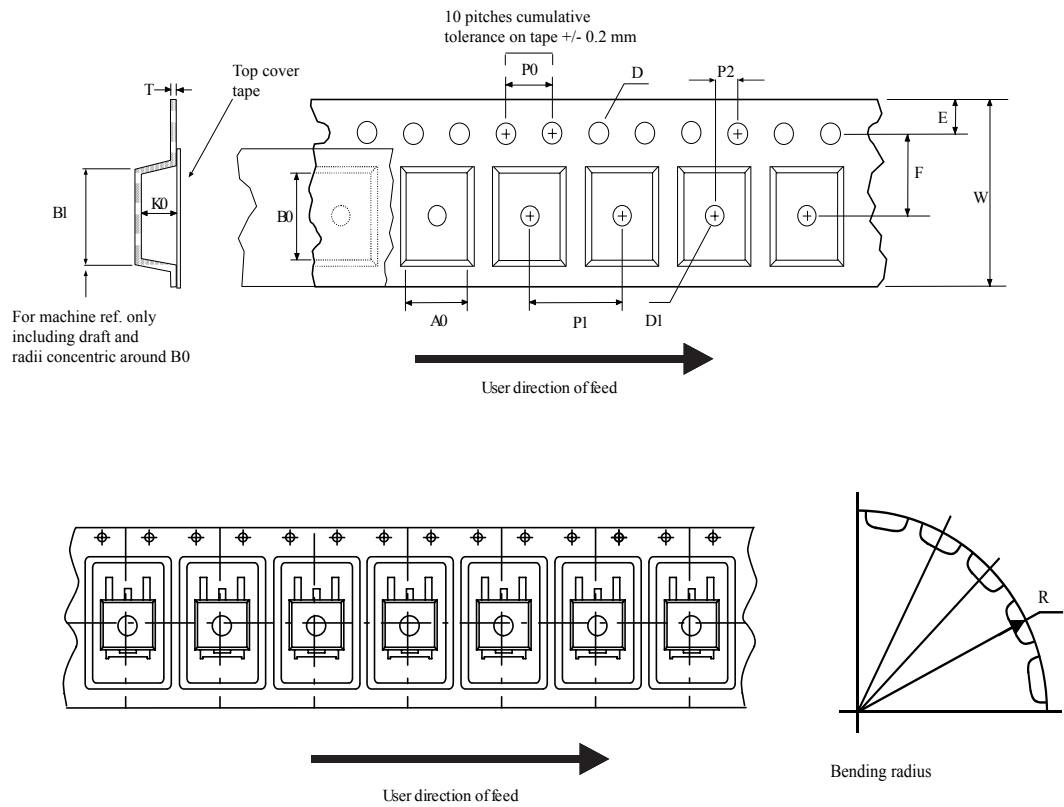
- Overall Width:** 6.3
- Overall Height:** 11.2
- Top Section:** A rectangular section with a width of 6.3 and a height of 6.5, filled with diagonal hatching.
- Bottom Section:** A rectangular section with a width of 4.572 and a height of 2.9, also filled with diagonal hatching.
- Left Section:** A rectangular section with a width of 1.5 and a height of 2.9, filled with diagonal hatching.
- Dimensions:**
 - 6.3 (Overall Width)
 - 6.5 (Height of Top Section)
 - 11.2 (Overall Height)
 - 4.572 (Width of Bottom Section)
 - 2.9 (Height of Bottom Section)
 - 1.5 (Width of Left Section)
 - 1.8 MIN (Minimum distance between the left section and the bottom section)
- Section Lines:** The hatching indicates that the sections are cut through the part.
- Reference Markers:**
 - A black triangle pointing to the left, labeled 'A' in a box, is located at the bottom center.
 - A black triangle pointing to the right, labeled 'B' in a box, is located at the top right.

2) The device must be positioned within $\oplus 0.05 \text{ A B}$

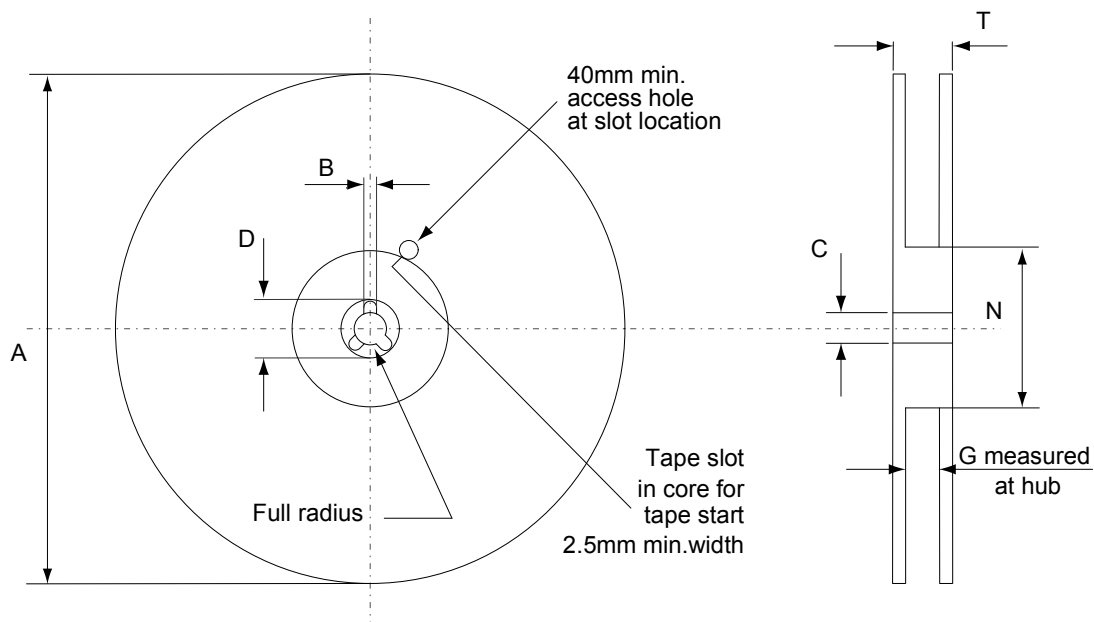
DS8813 - Rev 3
ed from Arrow.com.

4.2 DPAK (TO-252) packing information

Figure 22. DPAK (TO-252) tape outline



AM08852v1

Figure 23. DPAK (TO-252) reel outline


AM06038v1

Table 8. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Revision history

Table 9. Document revision history

Date	Revision	Changes
21-Dec-2011	1	First release.
10-Apr-2018	2	The part number STB6N62K3 has been moved to a separate datasheet. Removed maturity status indication from cover page. The document status is production data. Updated title and features in cover page. Updated <i>Section 1 Electrical ratings</i>, <i>Section 2 Electrical characteristics</i>, <i>Section 2.1 Electrical characteristics curves</i> and <i>Section 4 Package information</i>. Minor text changes.
16-May-2023	3	Added Section 4.1 DPAK (TO-252) type C3 package information. Minor text changes.

Contents

1	Electrical ratings	2
2	Electrical characteristics	3
2.1	Electrical characteristics curves	5
3	Test circuits	8
4	Package information	9
4.1	DPAK (TO-252) type C3 package information	9
4.2	DPAK (TO-252) packing information	12
	Revision history	14

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